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Invensas Announces That Sandia National Laboratories Has Licensed ZiBond and DBI Technologies for Advanced 3D Semiconductor Applications

Proven 2.5D and 3D Semiconductor Integration Technologies to be Incorporated in Next Generation National Laboratory Research

SAN JOSE, Calif.--(BUSINESS WIRE)-- Invensas Corporation, a wholly owned subsidiary of Tesser Technologies, Inc. (NASDAQ:TSRA), announced today that Sandia National Laboratories signed a new license agreement for ZiBond® and Direct Bond Interconnect (DBI®) technologies. With this license Sandia will have access to the most advanced 3D integration technologies available, for use in a wide range of semiconductor applications.

For more than 60 years, Sandia National Laboratories has been the premier science and engineering laboratory in the United States for national security and innovation. Working closely with U.S. government agencies, private industry and academic institutions, Sandia has led the charge to research, develop and deliver essential technologies used to solve many of the nation's most important security, climate change and sustainable energy challenges.

"The demand for cost-effective, versatile, 2.5D and 3D integration technologies has risen significantly, as research and commercial enterprises seek to expand overall performance and functionality of electronics products," said Craig Mitchell, President, Invensas Corporation. "ZiBond and DBI technologies are currently deployed in leading edge semiconductor products, and we are pleased to now make them available to Sandia, a premier government research institution."

ZiBond is a low-temperature homogeneous bonding technology that enables room temperature die or wafer-level 3D integration, without the need for the application of external pressure. DBI is a low-temperature, hybrid bonding technology with integrated electrical interconnects, that offers the industry's finest pitch and lowest cost-of-ownership 3D interconnect platform.

Both ZiBond and DBI deliver the fastest bonding throughput currently available in the industry, resulting in up to a 15x increase in wafer bonding throughput. Both technologies offer the thinnest available 2.5D and 3D semiconductor assemblies, while reducing wafer warpage, increasing reliability and improving thermal performance. Additionally, low processing temperatures significantly reduce equipment and process cost for high volume manufacturing.

For more information on ZiBond and DBI technologies as well as other Invensas solutions, please visit www.invensas.com or www.tessera.com.

About Tesser Technologies, Inc.

Tesser Technologies, Inc., including its Invensas and FotoNation subsidiaries, licenses technologies and intellectual property to customers for use in areas such as mobile computing and communications, memory and data storage, and 3D-IC technologies, among others. Our technologies include semiconductor packaging and interconnect solutions, and products and solutions for mobile and computational imaging, including our LifeFocus™, FaceTools™, FacePower™, FotoSavvy™, DigitalAperture™, face beautification, red-eye removal, High Dynamic Range, autofocus, panorama, and image stabilization intellectual property. For more information call +1.408.321.6000 or visit www.tessera.com or www.invensas.com.

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Safe Harbor Statement

This press release contains forward-looking statements, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements involve risks and uncertainties that could cause actual results to differ significantly from those projected, particularly with respect to the characteristics, benefits, and features of ZiBond and DBI technologies and the use of such technologies by Sandia National Laboratories. Material factors that may cause results to differ from the statements made include the plans or operations relating to the businesses

of Tessera Technologies, Inc. (the "Company"); market or industry conditions; changes in patent laws, regulation or enforcement, or other factors that might affect the Company's ability to protect or realize the value of its intellectual property; the expiration of license agreements and the cessation of related royalty income; the failure, inability or refusal of licensees to pay royalties; initiation, delays, setbacks or losses relating to the Company's intellectual property or intellectual property litigations, or invalidation or limitation of key patents; fluctuations in operating results due to the timing of new license agreements and royalties, or due to legal costs; the risk of a decline in demand for semiconductors and products utilizing FotoNation technologies; failure by the industry to use technologies covered by the Company's patents; the expiration of the Company's patents; the Company's ability to successfully complete and integrate acquisitions of businesses; the risk of loss of, or decreases in production orders from, customers of acquired businesses; financial and regulatory risks associated with the international nature of the Company's businesses; failure of the Company's products to achieve technological feasibility or profitability; failure to successfully commercialize the Company's products; changes in demand for the products of the Company's customers; limited opportunities to license technologies due to high concentration in the markets for semiconductors and related products and smartphone imaging; and the impact of competing technologies on the demand for the Company's technologies. You are cautioned not to place undue reliance on the forward-looking statements, which speak only as of the date of this release. The Company's filings with the Securities and Exchange Commission, including its Annual Report on Form 10-K for the year ended Dec. 31, 2015, include more information about factors that could affect the Company's financial results. The Company assumes no obligation to update information contained in this press release. Although this release may remain available on the Company's website or elsewhere, its continued availability does not indicate that the Company is reaffirming or confirming any of the information contained herein.

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